

Title (en)  
LIGHTWEIGHT CIRCUIT BOARD WITH CONDUCTIVE CONSTRAINING CORES

Title (de)  
LEICHTE LEITERPLATTE MIT LEITUNGSMATERIAL ENTHALTENDEN KERNEN

Title (fr)  
CIRCUIT IMPRIMÉ LÉGER DOTÉ DE NOYAUX DE LIMITATION CONDUCTEURS

Publication  
**EP 1360067 B1 20070221 (EN)**

Application  
**EP 01990176 A 20011211**

Priority  
• US 0148199 W 20011211  
• US 25499700 P 20001212

Abstract (en)  
[origin: US2012097431A1] Prepregs, laminates, printed wiring board structures and processes for constructing materials and printed wiring boards that enable the construction of printed wiring boards with improved thermal properties. In one embodiment, the prepregs include substrates impregnated with electrically and thermally conductive resins. In other embodiments, the prepregs have substrate materials that include carbon. In other embodiments, the prepregs include substrates impregnated with thermally conductive resins. In other embodiments, the printed wiring board structures include electrically and thermally conductive laminates that can act as ground and/or power planes.

IPC 8 full level  
**B32B 5/26** (2006.01); **C08J 5/24** (2006.01); **B32B 27/04** (2006.01); **B32B 27/12** (2006.01); **C08K 3/38** (2006.01); **C08K 9/08** (2006.01); **D03D 15/275** (2021.01); **H05K 1/02** (2006.01); **H05K 1/03** (2006.01); **H05K 3/46** (2006.01); **H05K 3/42** (2006.01); **H05K 3/44** (2006.01)

CPC (source: EP US)  
**B32B 5/26** (2013.01 - EP US); **B32B 27/04** (2013.01 - EP US); **B32B 27/12** (2013.01 - US); **C08K 3/38** (2013.01 - EP US); **C08K 9/08** (2013.01 - EP US); **H05K 1/0207** (2013.01 - EP US); **H05K 1/0366** (2013.01 - EP US); **H05K 1/0373** (2013.01 - EP US); **H05K 3/4641** (2013.01 - EP US); **B32B 2260/021** (2013.01 - US); **B32B 2262/101** (2013.01 - US); **B32B 2262/106** (2013.01 - US); **B32B 2307/202** (2013.01 - US); **B32B 2307/302** (2013.01 - US); **B32B 2457/00** (2013.01 - US); **C08K 2003/385** (2013.01 - EP US); **H05K 1/0206** (2013.01 - EP US); **H05K 3/429** (2013.01 - EP US); **H05K 3/445** (2013.01 - EP US); **H05K 3/4623** (2013.01 - EP US); **H05K 2201/0209** (2013.01 - EP US); **H05K 2201/0278** (2013.01 - EP US); **H05K 2201/0287** (2013.01 - EP US); **H05K 2201/0323** (2013.01 - EP US); **Y10S 428/901** (2013.01 - EP US); **Y10T 29/49124** (2015.01 - EP US); **Y10T 29/49165** (2015.01 - EP US); **Y10T 428/24917** (2015.01 - EP US); **Y10T 428/24994** (2015.04 - EP US); **Y10T 428/249942** (2015.04 - EP US); **Y10T 428/249945** (2015.04 - EP US); **Y10T 428/249946** (2015.04 - EP US); **Y10T 428/249947** (2015.04 - EP US); **Y10T 428/249951** (2015.04 - EP US); **Y10T 428/249952** (2015.04 - EP US); **Y10T 428/25** (2015.01 - EP US); **Y10T 428/292** (2015.01 - EP US); **Y10T 428/31504** (2015.04 - EP US); **Y10T 442/117** (2015.04 - EP US); **Y10T 442/2418** (2015.04 - EP US)

Designated contracting state (EPC)  
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)  
**WO 0247899 A1 20020620**; AT E354466 T1 20070315; AU 2904202 A 20020624; CN 100345679 C 20071031; CN 1486245 A 20040331; DE 60126832 D1 20070405; DE 60126832 T2 20071115; EP 1360067 A1 20031112; EP 1360067 A4 20040623; EP 1360067 B1 20070221; JP 2004515610 A 20040527; JP 2009164582 A 20090723; MY 143326 A 20110429; TW 200927803 A 20090701; TW I321518 B 20100311; TW I338703 B 20110311; US 2002157859 A1 20021031; US 2005019535 A1 20050127; US 2005019541 A1 20050127; US 2010319969 A1 20101223; US 2012097431 A1 20120426; US 6869664 B2 20050322; US 7635815 B2 20091222; US 7667142 B2 20100223; US 8097335 B2 20120117

DOCDB simple family (application)  
**US 0148199 W 20011211**; AT 01990176 T 20011211; AU 2904202 A 20011211; CN 01821947 A 20011211; DE 60126832 T 20011211; EP 01990176 A 20011211; JP 2002549457 A 20011211; JP 2008297101 A 20081120; MY PI20015654 A 20011212; TW 90130820 A 20011212; TW 98105098 A 20011212; US 201113339244 A 20111228; US 2050601 A 20011211; US 70845910 A 20100218; US 92161604 A 20040818; US 92164904 A 20040818